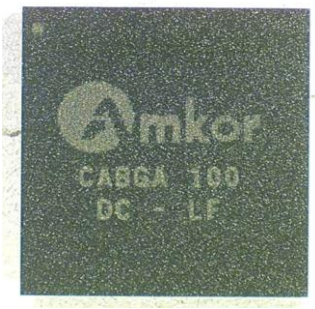
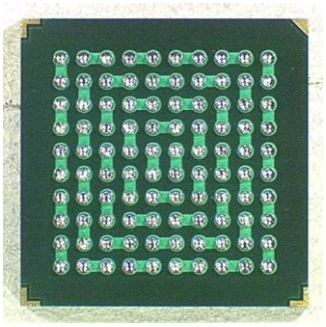
Package Characteristics: CABGA LF

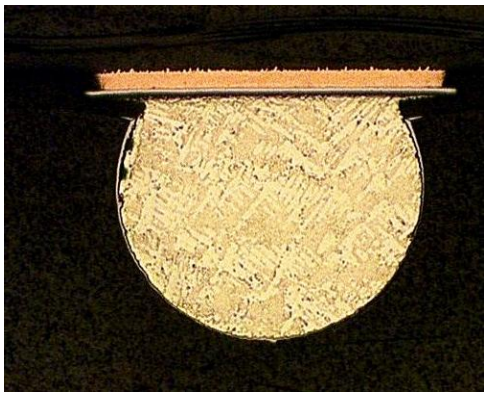


Top View

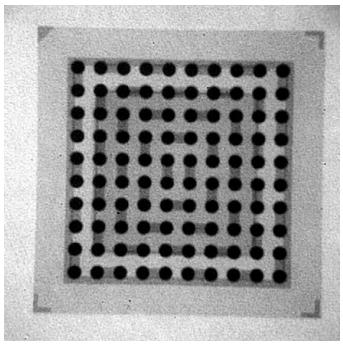


Bottom View

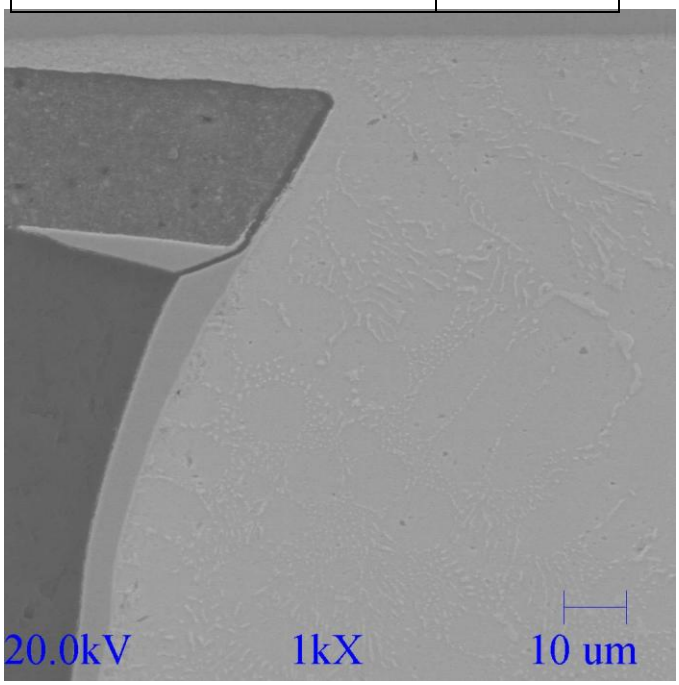
Feature	Value
Package Length	10.02 mm
Package Width	10.02 mm
Package Thickness	0.99 mm
Solder Ball Diameter	0.475 mm
Die Length	5.5 mm
Die Width	5.58 mm
Die Thickness	0.26 mm
Pitch	0.8 mm
Weight	0.2420 g
CTE	8.454 ppm/C
Width of Solder ball in contact with component pad	0.395 mm
Solderball Alloy (SEM estimation)	Sn4Ag.5Cu



Cross-section of solder ball



X-ray



SEM of solder ball cross-section